



US 20240213213A1

(19) **United States**

(12) **Patent Application Publication**
Jeng et al.

(10) **Pub. No.: US 2024/0213213 A1**

(43) **Pub. Date: Jun. 27, 2024**

(54) **EMBEDDED STRESS ABSORBER IN PACKAGE**

(60) Provisional application No. 63/085,222, filed on Sep. 30, 2020.

(71) Applicant: **Taiwan Semiconductor Manufacturing Co., Ltd.**, Hsinchu (TW)

Publication Classification

(51) **Int. Cl.**
H01L 23/00 (2006.01)
H01L 23/31 (2006.01)
H01L 23/498 (2006.01)
H01L 25/00 (2006.01)

(72) Inventors: **Shin-Puu Jeng**, Hsinchu (TW);
Chien-Sheng Chen, Hsinchu (TW);
Po-Yao Lin, Zhudong Township (TW);
Po-Chen Lai, Hsinchu (TW);
Shu-Shen Yeh, Taoyuan City (TW)

(52) **U.S. Cl.**
CPC **H01L 24/81** (2013.01); **H01L 23/3121** (2013.01); **H01L 23/49822** (2013.01); **H01L 24/96** (2013.01); **H01L 25/50** (2013.01)

(21) Appl. No.: **18/599,734**

(57) **ABSTRACT**

(22) Filed: **Mar. 8, 2024**

A method includes bonding a first package component over a second package component. The second package component includes a plurality of dielectric layers, and a plurality of redistribution lines in the plurality of dielectric layers. The method further includes dispensing a stress absorber on the second package component, curing the stress absorber, and forming an encapsulant on the second package component and the stress absorber.

Related U.S. Application Data

(60) Continuation of application No. 17/814,788, filed on Jul. 25, 2022, now Pat. No. 11,955,455, which is a division of application No. 17/149,348, filed on Jan. 14, 2021, now Pat. No. 11,532,593.

